

ABSTRACT

An epoxy resin composition for printed wiring boards which comprises as the essential components (a) an epoxy
5 resin obtained by epoxidizing a condensation product of a phenol with hydroxybenzaldehyde, (b) a condensation product of bisphenol A with formaldehyde, (c) a flame retardant, and (d) a curing accelerator, and a laminate for printed wiring boards which has a low hygroscopicity, a high heat
10 resistance, good high-temperature characteristics, a high resistance against electrolytic corrosion, a high resistance against color change due to heating, and a high Tg.